REMARKS

Reconsideration of the above-identified application in view of the amendments above and remarks below is respectfully requested.

Claims 1-7 and 9-18 are currently before the Examiner. Claims 1 and 16 have been amended and claim 15 has been cancelled herein.

Claims 1-5, 8-14 and 17 stand rejected under 35 U.S.C. 102(b) as being anticipated by Greene (US Pat. No. 6,344,520). The rejection is respectfully traversed.

In response, applicants have initially amended claim 1 to incorporate the subject matter of original claim 15 to further defined the epoxy resin as derived from the reaction of an epihalohydrin and a phenol or a phenol type compound. Greene *et al.* is directed to epoxy functional organopolysiloxane resins and coating systems. Greene *et. al.* only generally discloses that an optional curing agent accelerators may be utilized and do not use them in the reference's examples. In their Example Resin Formulation 1, Greene *et al.* utilize KOH for condensing Si-O-R groups to Si-O-Si groups. Therefore, Greene *et al.* do not teach or suggest the use of alkali metal containing compounds as a cure accelerators utilized in conjunction with the epoxy resins as described in claim 1, as amended, or that this use would result in resin coated articles having enhanced thermal properties such as improved resistance to elevated temperatures as desired, for example, in printed circuit board applications.

Claims 1, 3-7 and 9-18 stand rejected under 35 U.S.C. 102(b) as being anticipated by Allen (U.S. Patent No. 4,393,181). The rejection is respectfully traversed.

In response, applicants state that Allen is directed to specific curing agents which are polyfunctional phenolic adducts of polyhydric phenols and amino-triazines. At column 4, lines 58-68, cited by the Examiner, Allen only generally discloses hydroxides of alkaline earth and

alkali metals as "curing agent accelerator" to be utilized in conjunction with the polyfunctional phenolic adducts of polyhydric phenols and amino-triazines. Allen expressly teaches that such curing agent accelerators are "not preferred." Allen also expressly teaches that imidazoles are preferred and utilized 2-methylimidazole in his Examples. By contrast, referring to the examples of the present invention, applicants have illustrated that replacing the imidazole accelerator with alkali metal containing cure accelerator compound gave increased thermal resistance as measured by delamination time at 260°C while maintaining comparable laminate glass transition temperature. Therefore, Allen does not teach or suggest, and actually teaches away from, a process of using of alkali metal containing compounds as a cure accelerators as described in claim 1, or that such a process would result in resin coated articles having enhanced thermal properties in, for example, printed circuit board applications.

Claim 2 stands rejected under 35 U.S.C. 103(a) as being uppatent able over Allen (U.S. Patent No. 4,393,181) in view of Seltzer et al (US Pat. No. 4,168,364). The rejection is respectfully traversed.

Referring to the discussion above regarding Allen, Seltzer *et al.* is directed to cyanamides of organic primary amines as curing agents. As with Allen, the Examples of Seltzer *et al.* utilize only imidazole as a curing agent catalyst. Therefore, the combination does not cure the deficiency that Allen does not teach or suggest that use of the alkali metal cure accelerators, in place of imidazoles, would result in resin coated articles having enhanced thermal properties.

In light of the above amendments and remarks, it is respectfully submitted that the pending claims of the present application are in condition for allowance. If the Examiner has any questions or requires additional information, he is invited to contact the undersigned.

Respectfully submitted,

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